

ELECTROFORMED BLADES

1200 SERIES

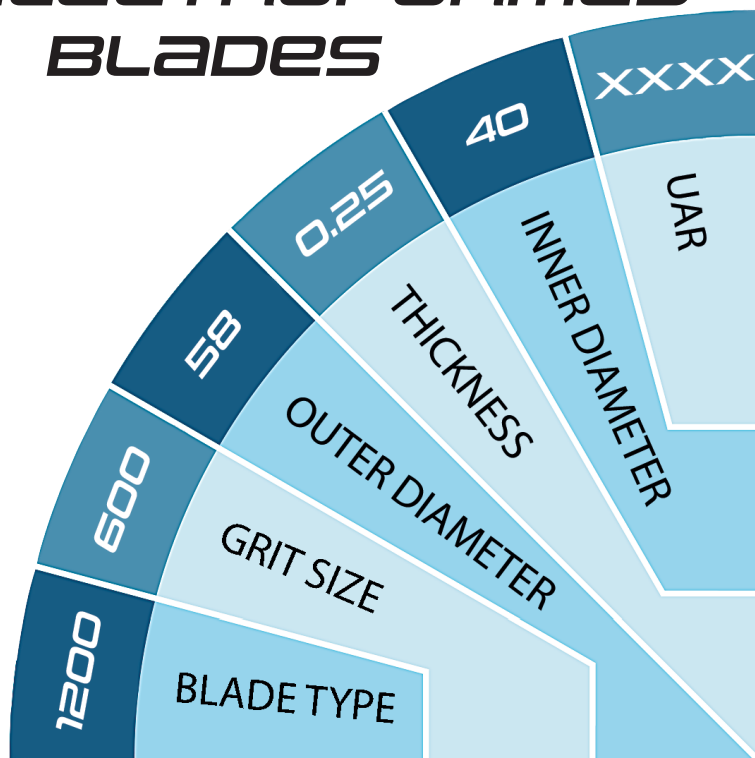


APPLICATIONS

Silicon, GaAs, softer ceramics (e.g. PZT), various semiconductor packages. Applications for easier to cut materials requiring long blade life performance

1200 SERIES electroformed dicing blades (also referred to as “nickel bonded” blades) contain hard wearing, tightly bonded diamonds to give long life and lower cost of ownership. The electroforming process bonds the diamonds together such that the overall diameter and edge profile of the blade is largely maintained. The inherent strength of an electroformed blade means thin blade widths are often selected to reduce substrate waste and to navigate fine circuitry or produce fine features

ELECTROFORMED BLADES



BLADE TYPE	GRIT SIZE	OUTER DIAMETER	THICKNESS	INNER DIAMETER	UAR
1200 Electroformed	3000 - 2/6um 2000 - 4/8um 1500 - 5/10um 1200 - 6/12um 1000 - 8/16um 800 - 10/20um 700 - 12/25um 600 - 20/30um 500 - 30/40um 400 - 40/60um	50 - 140mm	0.025 - 0.30mm	40.00mm	UAR- Unique Application Reference, - unique code that incorporates a number of parameters to suit your application.*

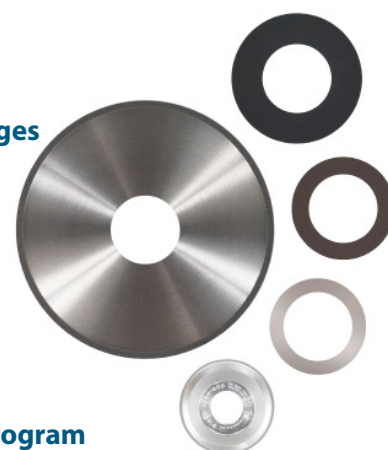
* Options available on bond type, concentration and additive ingredients

Loadpoint Expertise

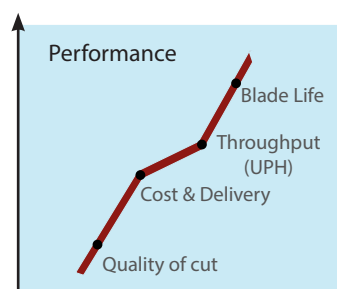
Our customers trust Loadpoint to help them develop class-leading products. We have helped many customers develop task orientated solutions for ultrasound scanners, inkjet printers, SAW filters, MEMS devices and a whole range of silicon based products.

Loadpoint Blade Ranges

- Resin Blade
- Hubbed Blade
- Resin on steel core
- Electroformed Blade
- Metal Blade
- Vitriified Blade



Blade Optimisation Program



Loadpoint can optimise a blade for any process based on any number of target objectives.

Let us know your dicing challenges and we will put together a program to enhance your process.

Micromachining solutions for:

SEMICONDUCTORS	OPTICAL
ELECTRONICS	MEDICAL/ULTRASOUND
FERRO-ELECTRONICS	SOLAR
OPTO-ELECTRONICS	SONAR